



CENTRE FOR MATERIALS FOR ELECTRONICS TECHNOLOGY (C-MET)
(Scientific Society, Ministry of Electronics & Information Technology, MeitY, Govt. of India)
Panchawati, Off. Dr. Homi Bhabha Road, Pashan, Pune- 411 008, INDIA

NOTICE OF INVITATION OF EXPRESSION OF INTEREST

Notification No: CMET/PUNE/2026/

Subject: Expression of Interest for the identification of Development cum Production industry (DcPP) partners for the joint submission of a project towards the Development of Advanced Photonics Packaging Technologies using Additive Manufacturing.

1. The objective of the Expression of Interests (EOI) –

The objective of this Expression of Interest (EOI) is to identify and empanel suitable Indian Industry Partners, Start-ups, MSMEs, OEMs, System Integrators, Research Organizations, and End Users for participation as Development-cum-Production Partners (DcPPs) in the proposed project entitled “Establishment of Additive Packaging Center (A-PACK Center) at C-MET, Pune (Phase-2 Technology Development)”.

2. EOI Issuing Authority –

Centre for Materials for Electronics Technology (C-MET), Pune

(An Autonomous Scientific Society under the Ministry of Electronics and Information Technology (MeitY), Government of India)

Panchawati, Off Pashan Road,

Pune – 411008,

Maharashtra, India

It is intended to find and shortlist the bidders through this EOI, which shall be final, and C-MET, Pune, reserves the right to reject any of all the bids without assigning any reason.

Sr. No.	Item	Description
1	Project Title	Expression of Interest for the identification of Development cum Production industry (DcPP) partners for the joint submission of a project Establishment of an integrated indigenous photonics packaging ecosystem encompassing: • Advanced photonics packaging materials and feedstocks • Multi-material DLP/VAT additive manufacturing platforms • AI-assisted DfAM and package design workflows • Reliability assessment and qualification frameworks • Pilot-line manufacturing and industry-transferable packaging solutions

The initiative aims to establish a scalable, intelligent, and industry-ready photonics packaging platform capable of supporting next-generation applications in silicon photonics, optical communications, AI data center interconnects, co-packaged optics, defence systems, aerospace systems, and strategic electronics.

2	EOI No. & Date	CMET/PUNE/2026-27/ PIC/01 dated: 5th August 2026
3	Project Initiator Details Department	Centre for Materials for Electronics Technology (C-MET), (Scientific Society under Ministry of Electronics & IT, Govt. of India), Pashan Road, Pune - 411008, Maharashtra, India Tel: +91-20-2589 8390
4	Contact Person Details	Project Coordinator – For technical queries Dr. Shany Joseph (Scientist E), C-MET Pune, Maharashtra, India 411008 Email: shany@cmet.gov.in Phone: +91-20-2589 8724 (Ext. 206)
5	Submission of Proposal	By email. Additionally, Hard copies to be sent by post to CMET, Pune

Tentative Calendar of Events

Sr. No.	Milestone	Date and time (dd-mm-yyyy, hh:mm)
1	Release of Expression of Interest (EOI)	05/08/2026, 09:00
2	Last date for submission of written questions by the bidders	10/08/2026, 17:30
3	Response to the queries	17/08/2026, 17:30
4	Last date for the submission of the EOI response	23/08/2026, 17:30
5	Opening of the EOI Responses	25/08/2026, 09:00
6	Declaration of the shortlisted firms	31/08/2026, 17:30

ANNEXURES

- Annexure-I (A):** Basic Company Details
- Annexure I (B):** Interested Industry Partner Information Proforma
- Annexure-II:** Non-Disclosure Agreement (NDA) Format
- Annexure-III:** Compliance Statement Template
- Annexure-IV:** Technical Capability Declaration
- Annexure-V:** Financial Details Format
- Annexure-VI:** Non-Blacklisting Affidavit Format

CRITICAL DATES:

Document Submission Start Date: 05/08/2026, 09:00 hrs
Document Submission End Date: 23/08/2026, 17:30 hrs

1. INTRODUCTION

The Centre for Materials for Electronics Technology (C-MET), Pune is implementing a proposed national-level R&D program for the establishment of an “Additive Packaging Center (A-PACK Center)” focused on development of advanced photonics packaging technologies using additive manufacturing.

The project builds upon the successful completion of Phase-1 activities under the CoE-AM initiative, wherein indigenous photo-curable LTCC materials, multi-material DLP-based additive manufacturing systems, and proof-of-concept photonic packaging structures were developed and validated up to Technology Readiness Level (TRL)-4.

Phase-2 aims to advance these capabilities toward TRL-6 validated photonic packaging modules through development of advanced material systems, indigenous additive manufacturing platforms, AI-enabled design frameworks, pilot manufacturing infrastructure, and application-specific packaging solutions for Photonic Integrated Circuits (PICs).

To facilitate industry participation, accelerate technology translation, and ensure commercialization readiness, C-MET invites Expressions of Interest from eligible Industry Partners for participation as Development-cum-Production Partners (DcPPs).

The proposed A-PACK Center aims to establish indigenous capabilities in advanced photonics packaging technologies based on additive manufacturing (Vat Polymerization / DLP-based technologies) for Photonic Integrated Circuits (PICs).

The EOI seeks industry participation in the following technology domains:

- a. Development of advanced LTCC and photonics packaging materials, including dielectric, conductive, optical, and thermal management.
- b. Development and commercialization of multi-material Vat Polymerization (DLP-based) additive manufacturing systems for photonics packaging applications.
- c. Design and validation of photonics packaging solutions for photonic devices.
- d. Development of AI-enabled Design for Additive Manufacturing (DfAM) tools and simulation platforms.
- e. Establishment of pilot-line manufacturing capabilities and support for technology transfer, product realization, commercialization, and deployment.
- f. Participation as end-users for validation, qualification, field deployment, and commercialization of technologies emerging from the A-PACK Center.

Through this EOI, C-MET seeks to identify suitable Industry Partners interested in a joint project submission for the establishment of an Additive Packaging Center (A-PACK Center) focused on the development of advanced photonics packaging technologies using Additive Manufacturing (Vat Photopolymerization/DLP-based technologies) for Photonic Integrated Circuits (PICs).

In this context, C-MET Pune invites Expression of Interest (EOI) from eligible Indian Companies, Start-ups, MSMEs, OEMs, System Integrators, Research Organizations, Testing Laboratories, and End Users to participate as Interested Industry Partners / Development-cum-Production Partners (DcPPs) for the joint submission of the proposed project and subsequent technology development activities.

The selected Industry Partner(s) shall collaborate with C-MET in the design, development, testing, validation, pilot manufacturing, qualification, deployment, and commercialization of technologies emerging from the proposed A-PACK Center. Upon successful completion of the project and subject to applicable Government of India and MeitY policies, the selected partner(s) may obtain non-exclusive Technology Transfer (ToT) from C-MET for manufacturing, deployment, and commercialization of the developed technologies for academic institutions, R&D laboratories, industries, strategic sectors, and government organizations across India.

This Expression of Interest is issued solely for the purpose of identifying potential Industry Partners for collaboration with C-MET. Submission of an EOI by any Interested Industry Partner shall not create any legally binding obligation on C-MET to enter into any partnership, consortium arrangement, Technology Transfer agreement, funding arrangement, or contractual commitment. C-MET reserves the right to accept, reject, modify, shortlist, or cancel the EOI process, either wholly or partially, at any stage without assigning any reason whatsoever.

The selected partners may participate in joint development, pilot production, testing, validation, manufacturing scale-up, and commercialization of technologies developed under the proposed project. Areas of industry participation are:

Category A

Materials Development Partners

Desired expertise:

- LTCC Materials
- Ceramic Materials
- Conductive Materials
- Optical Materials
- Thermal Interface Materials
- AI based Material discovery and Digital Twinning

Category B

Additive Manufacturing Equipment Partners

Desired expertise:

- DfAM
- DLP Systems
- Precision Motion Systems
- Industrial Automation
- Embedded Systems
- Process Integration

Category C

Photonics Packaging Partners

Desired expertise:

- Fiber Alignment
- Optical Packaging
- Hermetic Packaging
- Photonics integrated circuits
- Reliability Testing

Category D

End Users and System Integrators

Domains:

- Telecom
- Defence
- Aerospace
- Semiconductor Industry

- Strategic Electronics
- Medical Electronics

2. ELIGIBILITY CRITERIA

2.1. General Eligibility Criteria

Interested Industry Partners shall:

- a) Be incorporated/registered in India under the Companies Act, LLP Act, Partnership Act, MSME Act, or other applicable statutes.
- b) Possess valid PAN, GST, and statutory registrations.
- c) Not be blacklisted, debarred, or banned by any Central Government, State Government, PSU, Autonomous Body, or Research Organization.
- d) Have sound financial standing and operational capability.
- e) Demonstrate willingness to participate in technology development, manufacturing, testing, validation, commercialization, or deployment activities.

2.2. Technical Qualification – Criteria for Interested Industry Partners

Interested Industry Partners should possess expertise in one or more of the following areas:

- a) Advanced materials development (ceramics, LTCC, glass-ceramics, photopolymers, conductive materials, and thermal management materials).
- b) Additive manufacturing systems, Vat Polymerization, DLP-based printing technologies, automation, robotics, process monitoring, or machine development.
- c) Photonics packaging, optoelectronics packaging, semiconductor packaging, precision assembly, alignment, testing, and reliability evaluation.
- d) Optical design, simulation, AI-enabled design tools, CAD/CAM, DfAM, ADK development, or multiphysics modeling.
- e) Pilot manufacturing, process engineering, product development, qualification, certification, and commercialization.
- f) End-user industries related to photonics, telecom, defense, aerospace, medical, sensing, semiconductor manufacturing, or advanced electronics.

Preference may be given to organizations possessing prior experience in photonics, additive manufacturing, electronics packaging, LTCC technologies, or related domains.

2.3. Disclaimer

This EOI is intended solely for information gathering and identification of potential Development-cum-Production Partners (DcPPs).

Issuance of this EOI does not constitute a commitment by C-MET to award any contract, funding support, partnership agreement, technology transfer arrangement, or procurement order.

C-MET reserves the right to accept, reject, modify, suspend, or cancel the EOI process at any stage without assigning any reason.

3. EVALUATION PROCESS

The submitted EOIs shall be evaluated by a duly constituted committee of experts from C-MET and/or other competent authorities.

Evaluation may include assessment of:

- Technical capability and expertise.
- Relevant experience and project execution capability.
- Infrastructure and manufacturing facilities.
- Research and development capabilities.
- Financial strength and sustainability.
- Commercialization potential.
- Alignment with project objectives.
- End-user requirements and market reach.

C-MET may conduct presentations, technical discussions, site visits, or additional interactions with shortlisted organizations before final selection.

4. INTELLECTUAL PROPERTY RIGHTS

The Intellectual Property Rights (IPR) arising from the project shall be governed by applicable Government of India, MeitY, and C-MET policies.

The project is expected to generate intellectual property related to:

- Advanced LTCC material systems.
- Multi-material additive manufacturing processes.
- Conductive and optical material formulations.
- AI-enabled DfAM tools.
- Assembly Design Kits (ADKs).
- Photonics packaging architectures.
- Process optimization methodologies.

Detailed IPR ownership, licensing, technology transfer, commercialization rights, and revenue-sharing mechanisms shall be finalized at subsequent stages in accordance with applicable policies and mutually agreed terms.

5. TERMS AND CONDITIONS

5.1. General Terms

- Participation in this EOI is voluntary.
- Submission of EOI does not guarantee selection.
- C-MET may seek additional information at any stage.
- All information provided shall be treated in accordance with applicable confidentiality requirements.
- Selected partners may be required to execute Non-Disclosure Agreements (NDAs) and other legal documents.

5.2. Submission Requirements

Interested Industry Partners shall submit:

- Completed Annexure-I(A) and Annexure-I(B).
- Company profile.
- Technical capability details.
- Financial information.
- Compliance statement.
- Non-blacklisting affidavit.
- Supporting technical and commercial documents.

5.3. Disqualification Criteria

An EOI may be rejected if:

- Required information is incomplete.
- False or misleading information is provided.
- Eligibility criteria are not satisfied.
- Required declarations are not furnished.
- The organization is blacklisted, insolvent, or under legal restrictions.
- Submission is received after the prescribed deadline.

6. SUBMISSION DETAILS

6.1. How to Submit

Interested Industry Partners may submit their EOI along with the detailed information requested in Annexure – I, with supporting documentary proofs to the address given below.

Physical Submission: Eoi responses should be submitted in a sealed envelope clearly marked with: Expression of Interest for the identification of Development cum Production industry (DcPP) partners for the joint submission of a project towards the development of Establishment of Additive Packaging Center (A-PACK Center) at C-MET, Pune (Phase-2 Technology Development).

Eoi Reference Number: **CMET/PUNE/2026-27/ PIC/01 dated: 5th August 2026**

Company Name and Contact Details

2. Email Submission: Soft copy may also be submitted via email to the address mentioned below with the subject line: "Expression of Interest for the identification of Development cum Production industry (DcPP) partners for the joint submission of a project towards the Establishment of Additive Packaging Center (A-PACK Center) at C-MET, Pune (Phase-2 Technology Development)."

6.2. Submission Address

Physical Submission:

The Centre Head Centre for Materials for Electronics Technology (C-MET) (Scientific Society under Ministry of Electronics & IT, Govt. of India) Pashan Road, Pune - 411008, Maharashtra, India Tel: +91-20-2589 8390

Email Submission: shany@cmet.gov.in

Copy to: admn-pune@cmet.gov.in

Last Date of Submission: 23/08/2026 (Tentative) **Time:** 5:30 PM IST

Late submissions will not be entertained under any circumstances.

7. CONTACT INFORMATION

For any clarifications or queries regarding this Eoi, please contact:

Project Coordinator – For technical queries Dr. Shany Joseph (Scientist E), Centre for Materials for Electronics Technology (C-MET) Pune, Maharashtra, India 411008

Email: shany@cmet.gov.in

Phone: +91-20-2589 8724 (Ext. 206)

In-Charge Administration Contact: For administrative queries. In-Charge, Admin.

Email: admn-pune@cmet.gov.in

Phone: +91-20-2589 8390

Office Hours: Monday to Friday, 9:00 AM to 5:30 PM (Excluding Public Holidays)

Date of Issue:

Place: Pune

Centre Head, C-MET Pune

Note: This is an Expression of Interest only and does not constitute an offer or commitment by C-MET. C-MET reserves all rights to modify, cancel, or reissue this EoI at its sole discretion.

8. APPEAL / GRIEVANCE MECHANISM

Aggrieved Interested Industry Partners may submit a written representation to the Centre Head, C-MET Pune, within 7 days of the result declaration. The decision of the Centre Head, C-MET Pune, shall be final.

Eol - Annexure-I (A): Details to be furnished with Eol

1	Name of the Company	
	Type of the Company PSU/Public Ltd/Private Ltd/Registered Partnership firm/Others (specify)	
	Certificate of Registration /Incorporation No. (<i>Attach a copy of the Certificate</i>)	
	Address of the Registered Office	
	Name & Designation of Contact Person	
	Address with telephone No. & Email ID of Contact Person	
	Website address	
	Products/Services handled by the Company	
	No. of years of experience in the related area justified by orders executed	
	The last three years (<i>Attach copy of the audited statements</i>)	2023-2024 2024-2025 2025-2026
	Details of Income Tax Registration, GST registration, and other applicable registrations	
	PAN number	
	Available Manpower	Managerial: Engineers/Scientists: Technically skilled: Semi-Skilled: Un –skilled:
	Testing and Calibration Facility (Infrastructure and Equipment)	
	ISO certification/ In-house QA if any	
	Any other information, The Organization wishes to provide	
Declaration		
I/We hereby declare that the information given in the Eol and documents attached herewith are true & correct to the best of my/our knowledge and belief. I/We agree that in case any particulars are found incorrect at any time, C-MET has the right to cancel our EOI submission and/or any subsequent selection as development-cum-Production Partner (DcPP) for the proposed project towards the Development of Advanced Photonics Packaging Technologies using Additive Manufacturing, and all the payments, if any, to C-MET shall stand forfeited.		
Date :		
Place:		
Authorized Signatory (with official seal)		

Annexure-I (B): Interested Industry Partners Information Proforma

A. Organization Details

1. Legal Name of Organization: _____
2. Trade Name (if different): _____
3. Type of Organization: ☐ Proprietorship ☐ Partnership ☐ Private Ltd ☐ Public Ltd ☐ LLP ☐ Others (specify) _____
4. Year of Establishment: _____
5. Country of Registration: _____
6. Registration Number: _____
7. PAN Number: _____
8. GST Number: _____
9. TAN Number: _____

B. Contact Information

1. Registered Office Address: _____
2. Corporate Office Address: _____
3. PIN Code: _____
4. Telephone: _____
5. Email (Official): _____
6. Website: _____

C. Authorized Signatory Details

1. Name: _____
2. Designation: _____
3. Contact Number: _____
4. Email: _____
5. Authorization Letter Attached: ☐ Yes ☐ No

D. Key Personnel for This Project

1. Project Manager Name: _____
2. Technical Lead Name: _____
3. Contact Details: _____

E. Banking Details

1. Bank Name: _____
2. Branch Address: _____
3. Account Number: _____

4. IFSC Code: _____

5. Account Type: ☐ Current ☐ Savings

Annexure-II: Non-Disclosure Agreement (NDA) Format

NON-DISCLOSURE AGREEMENT

This Non-Disclosure Agreement ("Agreement") is entered into on this _____ day of _____ 20____ at _____.

BETWEEN:

C-MET, Pune (hereinafter referred to as "Disclosing Party"/ "Receiving Party") Address: C-MET Pune, Maharashtra, India 411008

AND

[Interested Industry Partners Name] (hereinafter referred to as "Receiving Party" / "Disclosing Party") Address: _____

WHEREAS the Disclosing Party intends to share certain confidential and proprietary information related to [Project Name] for Expression of Interest (EOI) evaluation.

NOW THEREFORE, in consideration of the mutual covenants and agreements, the parties agree as follows:

1. Definition of Confidential Information Confidential Information includes all technical, scientific, commercial, and financial data, documents, specifications, drawings, designs, processes, know-how, project plans, and any other information disclosed by the Disclosing Party.

2. Obligations of the Receiving Party: The Receiving Party agrees to:

- Maintain strict confidentiality of all information received
- Use the information solely for EOI evaluation purposes
- Not disclose information to any third party without written consent
- Limit access to information on a need-to-know basis
- Return or destroy all confidential materials upon request

3. Exclusions This Agreement does not apply to information that:

- Is publicly available through no breach of this Agreement
- Was rightfully possessed before disclosure
- Is independently developed without the use of confidential information
- Is required to be disclosed by law or court order

4. Term This Agreement shall remain in effect for a period of _____ years from the date of signing.

5. Remedies The Receiving Party acknowledges that breach of this Agreement may cause irreparable harm, and the Disclosing Party shall be entitled to seek injunctive relief in addition to other remedies.

6. This Agreement shall be governed by and construed in accordance with the laws of India, and the courts at Pune, Maharashtra shall have exclusive jurisdiction.

For Disclosing Party: Signature: _____ Name: _____

Designation: _____ Date: _____

Seal: _____

For Receiving Party: Signature: _____ Name: _____

Designation: _____ Date: _____

Seal: _____

Annexure-III: Compliance Statement Template

COMPLIANCE STATEMENT

To, [Name of Organization] [Address]

Subject: Compliance Statement for EOI No. _____

Dear Sir/Madam,

We, [Vendor Name], having our registered office at [Address], hereby declare and confirm our compliance with the eligibility criteria and requirements specified in the Expression of Interest (EOI) document for [Project Name].

Technical Compliance:

S. No.	EOI Requirement	Compliance Status	Remarks
1.		☐ Yes ☐ No ☐ Partially	
2.		☐ Yes ☐ No ☐ Partially	
3.		☐ Yes ☐ No ☐ Partially	
4.		☐ Yes ☐ No ☐ Partially	
5.		☐ Yes ☐ No ☐ Partially	

Regulatory Compliance:

S. No.	Compliance Requirement	Status	Document Reference
1.	Valid Business Registration	☐ Yes ☐ No	
2.	GST Registration	☐ Yes ☐ No	
3.	PAN Card	☐ Yes ☐ No	
4.	ISO Certification (if applicable)	☐ Yes ☐ No	
5.	Industry-specific licenses	☐ Yes ☐ No	

Commercial Compliance:

- We accept the terms and conditions of the EOI: ☐ Yes ☐ No
- We have no conflict of interest: ☐ Confirmed
- We are not blacklisted by any government/PSU: ☐ Confirmed

Deviations (if any):

We understand that any false declaration may lead to disqualification and legal action.

For [Interested Industry Partners Name]

Signature: _____ Name: _____

Designation: _____ Company Seal: Date: _____

_____ Place: _____

Annexure-IV: Technical Capability Declaration

TECHNICAL CAPABILITY DECLARATION

A. Organizational Capabilities

1. Technical Expertise:
- Total Technical Staff: _____

• PhDs: _____ | M.Tech/M.Sc: _____ | B.Tech/B.Sc: _____

• Years of experience in relevant field: _____
2. Infrastructure:
- Laboratory Facilities: ☐ Yes ☐ No

• Testing Equipment: (List) _____

• Quality Control Setup: ☐ Yes ☐ No

• Certification: _____
3. Technology Partnerships:
- List of collaborations with research institutions: _____

• Technology licenses held: _____

B. Past Project Experience

S. No.	Project Name	Client	Duration	Project Value	Relevance to Current EOI
1.					
2.					
3.					

C. Key Technical Personnel

Name	Qualification	Specialization	Years of Experience	Role in Proposed Project

D. Research & Development Capabilities

- Annual R&D Budget: _____
- Number of Patents/Copyrights Filed/Granted: _____
- Ongoing Research Projects: _____

E. Quality Assurance

- Quality Management System: _____
- _____

F. Project Execution Methodology Brief description of approach to scientific projects (max 500 words):

G. Supporting Documents Attached: ☐ Company Profile ☐ Technical Team CVs ☐
Laboratory/Facility Photographs ☐ Equipment List with Specifications ☐ Quality Certificates ☐
Client Testimonials/Work Orders ☐ Publications/Patents (if applicable)

Declaration: I/We hereby declare that all information provided above is true and accurate to the best of my knowledge. I/We understand that any false information may result in disqualification.

For [Interested Industry Partners Name]

Signature: _____ Name: _____
Designation: _____ Company Seal: Date: _____

Annexure-V: Financial Details Format

FINANCIAL DETAILS FORMAT

A. Annual Turnover Details

Financial Year	Annual Turnover (INR)	Turnover from Similar Projects	Audited/Provisional
2025-26			
2024-25			
2023-24			

B. Profit & Loss Summary

Particulars	FY 2023-24	FY 2024-25	FY 2025-26
Total Revenue			

C. Balance Sheet Summary

Particulars	As on 31.03.2024	As on 31.03.2025	As on 31.03.2026
Total Assets			
Current Assets			
Total Liabilities			
Current Liabilities			

E. Banking Arrangements

1. Banker's Name: _____
2. Branch: _____
3. Type of Facilities Availded: _____
4. Credit Limit Sanctioned: _____
5. Outstanding Amount: _____

G. Tax Compliance

- Income Tax Return filed for last 3 years: ☐ Yes ☐ No
- Any tax demands pending: ☐ Yes ☐ No (If yes, provide details: _____)
- GST Returns filed regularly: ☐ Yes ☐ No

H. Financial Capacity for This Project

- Estimated Project Value: _____

● Available Working Capital: _____

● Proposed Financial Arrangement: _____

I. Documents Attached: ☐ Audited Financial Statements (last 3 years) ☐ Income Tax Returns (last 3 years) ☐ GST Returns (last 6 months) ☐ Bank Solvency Certificate ☐ CA Certificate for turnover
☐ Credit Rating Certificate (if applicable)

Declaration: I/ We hereby certify that the financial information provided above is true and correct as per our books of accounts and audited financial statements.

For [Interested Industry Partners Name]

Signature: _____ Name: _____

Designation: _____ Company Seal: Date: _____

Annexure-VI: Non-Blacklisting Affidavit Format

NON-BLACKLISTING AFFIDAVIT

AFFIDAVIT

I, _____ (Name), son/daughter/wife of _____, aged _____ years, residing at _____, being the Authorized Signatory of M/s _____ (Name of the Company), having its registered office at _____, do hereby solemnly affirm and declare as under:

1. That I am the authorized signatory of the above-named company and am competent to swear this affidavit on behalf of the company.
2. That our company/firm M/s _____ has submitted an Expression of Interest (EOI) in response to EOI No. _____ dated _____ for [Project Name].
3. That our company/firm has not been blacklisted, debarred, or banned by any Central Government/State Government/Public Sector Undertaking/Autonomous Body/Research Institution in India or abroad as on the date of submission of this EOI.
4. That no criminal proceedings are pending against our company/firm or its directors/partners/proprietors in any court of law.
5. That our company/firm has not been declared insolvent or bankrupt, and no insolvency proceedings are pending against us.
6. That our company/firm has not been involved in any fraudulent, corrupt, or unethical business practices.
7. That no investigation by any regulatory or investigative agency is currently ongoing against our company/firm or its promoters/directors.
8. That we have never been terminated from any contract due to non-performance or misrepresentation.
9. That we undertake to immediately inform C-MET if any of the above declarations become incorrect during the EOI evaluation process.
 - Disqualify our EOI without any prior notice
 - Terminate any contract awarded to us
 - Forfeit any performance security/earnest money deposit
 - Debar us from future opportunities
 - Take any legal action deemed appropriate
10. That all information provided in this affidavit is true and correct to the best of my knowledge and belief.

NOTARY PUBLIC

Sworn before me on this _____ day of _____ 20____ at _____.

Signature: _____ Name: _____ Notary
Registration No.: _____ Seal: _____

Note: This affidavit should be executed on non-judicial stamp paper of appropriate value as per state regulations (typically Rs. 100-500) and duly notarized.